		Oh Mout	DB	Time stamp	
L Number	Hits 690	Search Text (216/24).CCLS.	USPAT;	2004/05/05	12:18
_	090	(210/24).0000.	US-PGPUB;		
			EPO; JPO;		
			DERWENT;		
			IBM_TDB		
_	135	(216/26).CCLS.	USPAT;	2004/05/04	09:27
			US-PGPUB;		
			EPO; JPO;		
			DERWENT;		
			IBM TDB	2004/05/04	00.20
-	83	(216/31).CCLS.	USPAT; US-PGPUB;	2004/03/04	09.20
			EPO; JPO;		
			DERWENT;		
		·	IBM TDB		ļ
l _	126	(216/55).CCLS.	USPAT;	2004/05/04	09:29
	120	(220,00,0022)	US-PGPUB;		
			EPO; JPO;		
			DERWENT;		1
			IBM_TDB		
-	170	(216/85).CCLS.	USPAT;	2004/05/10	11:56
			US-PGPUB;	+	
			EPO; JPO;		
			DERWENT;		
		(01.6./07), 007.0	IBM_TDB USPAT;	2004/05/04	00.20
-	307	(216/87).CCLS.	US-PGPUB;	2004/03/04	07.23
			EPO; JPO;		
			DERWENT;		
			IBM TDB		
_	106	(216/94).CCLS.	USPAT;	2004/05/04	09:30
	155	(100)	US-PGPUB;		
			EPO; JPO;		
			DERWENT;		
			IBM_TDB		
-	552	(216/97).CCLS.	USPAT;	2004/05/12	16:26
			US-PGPUB;		
			EPO; JPO;		
			DERWENT;		
	2	("5057184").PN	IBM_TDB USPAT;	2004/05/04	09.31
-		("5057184").PN.	US-PGPUB;	2004/05/04	03.31
-			EPO; JPO;		
			DERWENT;		
			IBM TDB		
_	463	(216/65).CCLS.	USPĀT;	2004/05/04	09:33
			US-PGPUB;		
			EPO; JPO;		
			DERWENT;		
			IBM_TDB	2004/05/04	00.41
-	386	(etch\$3 and (heat\$3 or radiation) and	USPAT;	2004/05/04	09:41
		(computer or controller)).clm.	US-PGPUB;		
			EPO; JPO; DERWENT;		
1	1		IBM TDB		
_	129	(etch\$3 and (heat\$3 or radiation) and	USPAT;	2004/05/08	15:24
	129	(computer or controller) and (etchant or	US-PGPUB;		
1		solution or liquid or wet or	EPO; JPO;		
1		wet\$letch\$3)).clm.	DERWENT;		
			IBM_TDB	}	
-	263		USPĀT;	2004/05/04	09:51
		((216/31).CCLS.) or ((216/55).CCLS.) or	US-PGPUB;		
		((216/85).CCLS.) or ((216/87).CCLS.) or	EPO; JPO;		
		((216/94).CCLS.) or ((216/97).CCLS.)) and	DERWENT;		
	117	(computer or controller)	IBM_TDB USPAT;	2004/05/04	10.02
-	117	(((216/24).CCLS.) or ((216/26).CCLS.) or ((216/31).CCLS.) or ((216/55).CCLS.) or	US-PGPUB;	2004/03/04	10.02
		((216/31).CCLS.) or ((216/33).CCLS.) or ((216/87).CCLS.) or	EPO; JPO;		
1		((216/94).CCLS.) or ((216/97).CCLS.)) and	DERWENT;		
1		(heat\$3 with (local\$2 or specific or	IBM TDB		
		selected))			
		1	•	·	

-	26	("3833383" "4049944" "4289381"	USPAT	2004/05/04 09:54
		"4340617" "4489102" "4512638"		
		"4514479" "4523807" "4664940"		
		"4746934" "4778744" "4818661"		
		"4843031" "4857425" "4859496"		
		"4859548" "5250329" "5543251"		
		"5745221" "5748368" "5771098"		
		"5796004" "5810945" "RE36113"		
	100	"5955221" "5991075").PN. ((etchant or (etch\$3 adj solution)) and	USPAT;	2004/05/12 15:50
-	102	(heat\$3 with (local\$2 or specific or	US-PGPUB;	2001, 00, 12 10.00
		selected))).clm.	EPO; JPO;	
		Selected///.cim.	DERWENT;	
			IBM TDB	
_	696	((216/55).CCLS.) or ((216/85).CCLS.) or	USPĀT;	2004/05/12 16:26
		((216/87).CCLS.) or ((216/94).CCLS.)	US-PGPUB;	
1			EPO; JPO;	
			DERWENT;	
		,	IBM_TDB	
_	171	laser-induced with etch\$3	USPAT;	2004/05/11 15:21
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
		(apparatus and etch\$3 and heater\$1 and	IBM_TDB USPAT:	2004/05/04 10:33
-	32	(apparatus and etcn\$3 and neater\$1 and rate).clm.	US-PGPUB;	2004/00/04 IU.00
		rate).Cim.	EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	194	(apparatus and etch\$3 and heater\$1).clm.	USPAT;	2004/05/12 13:31
	151	(apparated and observe and institution)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
_	186	(156/345.1).CCLS.	USPAT;	2004/05/04 10:35
		•	US-PGPUB;	
1			EPO; JPO;	
	1		DERWENT;	
	150	(15.6./2.45, 11.), GOT 0	IBM_TDB USPAT;	2004/05/04 10:40
-	150	(156/345.11).CCLS.	US-PGPUB;	2004703704 10.40
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	70	(156/345.22).CCLS.	USPAT;	2004/05/04 11:00
	"	· · · · · · · · · · · · · · · · · · ·	US-PGPUB;	
			EPO; JPO;	
1			DERWENT;	
1			IBM_TDB	
-	248	(156/345.24).CCLS.	USPAT;	2004/05/04 10:37
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	100	(150/245 27) 0010	IBM_TDB USPAT;	2004/05/10 11:49
-	106	(156/345.27).CCLS.	USPAT; US-PGPUB;	2004/03/10 11:49
			EPO; JPO;	
			DERWENT;	
1			IBM TDB	
_	143	(156/345.28).CCLS.	USPAT;	2004/05/04 10:37
1			US-PGPUB;	
1			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	91	(156/345.15).CCLS.	USPAT;	2004/05/10 11:39
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	<u> </u>

_	215	((156/345.11).CCLS.) or	USPAT;	2004/05/04 10:58
		((156/345.22).CCLS.)	US-PGPUB;	
			EPO; JPO; DERWENT;	·
			IBM TDB	
l _	2	("6675817").PN.	USPAT;	2004/05/04 10:58
-	2	(0073017) . I N .	US-PGPUB;	2331, 33, 31 23133
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	38	(apparatus and etch\$3 and heater\$1 and	USPĀT;	2004/05/10 12:12
		(computer or controller)).clm.	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	1.0	(apparatus and etch\$3 and heater\$1 and	IBM_TDB USPAT;	2004/05/04 11:22
_	16	solution).clm.	US-PGPUB;	2004/05/04 11:22
		Solution) . Clin.	EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	30	radiation-induced with etch\$3	USPAT;	2004/05/04 11:25
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	2004/05/04 15:05
-	29	etch\$3 same apparatus same heater\$1 same	USPAT;	2004/05/04 15:05
		tank	US-PGPUB; EPO; JPO;	
			DERWENT;	
			IBM TDB	
	173	etch\$3 same heater\$1 same tank	USPAT;	2004/05/04 11:28
		·	US-PGPUB;	
			EPO; JPO;	
	1		DERWENT;	
	1		IBM_TDB	0004/07/04
_	4	("2143796" "3023139" "3284181"	USPAT	2004/05/04 14:41
	0.5	"5246540").PN.	HCDAT-	2004/05/04 14:42
-	95	(glass and etch\$3 and heater\$1).clm.	USPAT; US-PGPUB;	2004/03/04 14:42
	1		EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	1495	(glass and etch\$3 and heat\$3).clm.	USPĀT;	2004/05/04 14:42
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	421	(otab\$3 and apparatus and (liquid ar	IBM_TDB USPAT;	2004/05/04 14:51
-	431	(etch\$3 and apparatus and (liquid or solution or wet\$8)).ti.	US-PGPUB;	2004/03/04 14:31
		SOLUCION OF MECAONICE.	EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	52	(etch\$3 and apparatus and (liquid or	USPĀT;	2004/05/04 14:47
		solution or wet\$8)).ti. and heat\$3	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	100		IBM_TDB	2004/05/04 14 50
_	136	(wet and etching and apparatus).ti.	USPAT;	2004/05/04 14:56
			US-PGPUB; EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	13	((wet with etch\$3) and (local\$4 with	USPĀT;	2004/05/04 15:14
		heat\$3)).ab.	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
		//11.	IBM_TDB	2004/05/11 15 25
-	19	, ,	USPAT;	2004/05/11 15:31
		and heater\$1 and (computer or	US-PGPUB;	
		controller)).clm.	EPO; JPO; DERWENT;	
			IBM TDB	
L	J	<u> </u>	1 100	

_	173	etch\$3 same heater\$1 same tank	USPAT; US-PGPUB;	2004/05/04 15:06
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	7	((liquid with etch\$3) and (local\$4 with	USPAT;	2004/05/04 15:14
1		heat\$3)).ab.	US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM TDB	1
	21	((solution with etch\$3) and (local\$4 with	USPAT;	2004/05/04 15:19
	21	heat\$3)).ab.	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	2004/05/04 16:09
-	335	((polish\$3 or etch\$3) and (local\$4 with	USPAT; US-PGPUB;	2004/05/04 16:09
		heat\$3)).ab.	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	911	((polish\$3 or etch\$3) and (select\$3 with	USPAT;	2004/05/04 16:10
ľ		heat\$3)).ab.	US-PGPUB;	
1			EPO; JPO;	
			DERWENT; IBM TDB	
_	281	((polish\$3 or etch\$3) and (select\$3 with	USPAT;	2004/05/04 16:11
	201	heat\$3 and (portion or area or	US-PGPUB;	
		region))).ab.	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
_	65	((boundary adj layer) and etch\$3).clm.	USPAT;	2004/05/05 11:55
			US-PGPUB; EPO; JPO;	·
			DERWENT;	
			IBM TDB	
_	505	menisc\$2 same etch\$3	USPAT;	2004/05/05 12:02
	+		US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
1_	110	menisc\$2 with etch\$3	IBM_TDB USPAT;	2004/05/05 11:59
	110	meniscyz with etchys	US-PGPUB;	2001/03/03 11:33
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	0004/05/05 10 10
-	4	marangoni and rushford.in.	USPAT;	2004/05/05 12:13
			US-PGPUB; EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	4	marangoni and britten.in.	USPĀT;	2004/05/05 12:00
			US-PGPUB;	
			EPO; JPO;	
			DERWENT; IBM TDB	
_	85	(menisc\$2 and etch\$3).clm.	USPAT;	2004/05/05 12:08
		indiana dedita), oring	US-PGPUB;	=551,55,55 12.00
			EPO; JPO;	
			DERWENT;	
		(IBM_TDB	0004/05/05 55 55
-	2216	(menisc\$2).ti.	USPAT;	2004/05/05 12:09
			US-PGPUB; EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	28	(menisc\$2).ti. and etch\$3	USPĀT;	2004/05/05 12:09
			US-PGPUB;	
			EPO; JPO;	
1			DERWENT;	
_	34	5660642.URPN.	IBM_TDB USPAT	2004/05/05 12:11
L	74	0000012.0KEH.	LOSINI	2004/03/03 12.11

-	30	marangoni same etch\$3	USPAT;	2004/05/05 12:13
			US-PGPUB; EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	77	(etch\$3 and heater\$1 and (computer or	USPAT;	2004/05/05 12:19
	1	controller)).clm.	US-PGPUB;	
		Gonerotton, , volum	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	96		USPĀT;	2004/05/05 12:23
		(element\$1 or electrode\$1))) and (computer	US-PGPUB;	
		or controller)).clm.	EPO; JPO;	
			DERWENT;	
			IBM_TDB	0004/05/05 10 04
_	922	(etch\$3 and (heater\$1 or (heat\$3 adj	USPAT;	2004/05/05 12:24
		(element\$1 or electrode\$1)))).clm.	US-PGPUB; EPO; JPO;	
			DERWENT;	
1			IBM TDB	
_	198	(etch\$3 and (liquid or solution) and	USPAT;	2004/05/05 12:26
1		(heater\$1 or (heat\$3 adj (element\$1 or	US-PGPUB;	
		electrode\$1)))).clm.	EPO; JPO;	
1			DERWENT;	
		·	IBM_TDB	
-	1467	(etch\$3 same (liquid or solution or wet))	USPĀT;	2004/05/05 12:28
		and ((heater\$1 or (heat\$3 adj (element\$1	US-PGPUB;	
		or electrode\$1)))).clm.	EPO; JPO;	
			DERWENT;	
	260	(124/61) 607.0	IBM_TDB	2004/05/05 12:39
-	362	(134/61).CCLS.	USPAT; US-PGPUB;	2004/05/05 12:39
}			EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	91	(134/88).CCLS.	USPAT;	2004/05/05 12:39
		(====	US-PGPUB;	
			EPO; JPO;	
	1		DERWENT;	
			IBM_TDB	
 -	52	(134/90).CCLS.	USPAT;	2004/05/05 12:40
			US-PGPUB;	
			EPO; JPO;	
-			DERWENT; IBM TDB	
	83	(124/94) CCI S	USPAT;	2004/05/10 11:54
	"3"	(134/84).CCLS.	US-PGPUB;	2004/05/10 11.54
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	496	(65/355).CCLS.	USPĀT;	2004/05/05 14:30
			US-PGPUB;	1
			EPO; JPO;	
			DERWENT;	
	365	(202/441) GGIG	IBM_TDB	2004/05/05 14 12
_	365	(392/441).CCLS.	USPAT; US-PGPUB;	2004/05/05 14:13
			EPO; JPO;	
			DERWENT;	
1			IBM TDB	
_	187	(219/628).CCLS.	USPĀT;	2004/05/12 11:33
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
1			IBM_TDB	
_	222	(219/656).CCLS.	USPAT;	2004/05/05 14:31
			US-PGPUB;	
	1		EPO; JPO;	
			DERWENT;	
L			IBM_TDB	1

-	502	(219/635).CCLS.	USPAT;	2004/05/05 14:31
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	i
			IBM_TDB	0004/05/05 14 20
-	100	(219/638).CCLS.	USPAT;	2004/05/05 14:32
			US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM TDB	
	320	(219/660).CCLS.	USPAT;	2004/05/05 14:32
-	320	(219/000).0003.	US-PGPUB;	2004/05/05 14.52
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	515	(219/672).CCLS.	USPAT;	2004/05/05 14:32
		(===, ====,	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	29	(((219/628).CCLS.) or ((219/656).CCLS.) or	USPAT;	2004/05/05 14:37
		((219/635).CCLS.) or ((219/638).CCLS.) or	US-PGPUB;	
		((219/660).CCLS.) or ((219/672).CCLS.))	EPO; JPO;	
		and etch\$3	DERWENT;	
			IBM_TDB	
-	180	((wet or liquid) adj etch\$3).ti. and	USPAT;	2004/05/05 14:41
		heat\$3	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	1
!	1.00	///wat an limid on colution\ noon2	IBM_TDB USPAT;	2004/05/05 14:47
_	466	(((wet or liquid or solution) near3 etch\$3) and (heat\$3 or laser) and (lens\$2	USPAT; US-PGPUB;	2004/05/05 14:4/
		or optic\$2 or glass)).clm.	EPO; JPO;	
		or operess or grass//.erm.	DERWENT;	
Ì			IBM TDB	
_	17	(((wet or liquid or solution) near3	USPAT;	2004/05/05 14:47
	1,	etch\$3) and (heat\$3 or laser) and (lens\$2	US-PGPUB;	2001, 00, 00 1111,
		or optic\$2 or glass)).ti.	EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	19	((liquid or solution or wet) and etch\$3	USPĀT;	2004/05/05 15:16
		and heater\$1 and (computer or	US-PGPUB;	
		controller)).clm.	EPO; JPO;	
			DERWENT;	•
			IBM_TDB	
-	96	(glass and etching and apparatus).ti.	USPAT;	2004/05/05 15:17
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
1_	705	 (glass and etching and apparatus).ti. or	IBM_TDB USPAT;	2004/05/05 15:18
-	103	(glass and etching and apparatus).ti. or (glass and etching and apparatus).ab. or	US-PGPUB;	2004/03/03 13:18
		(glass and etching and apparatus).clm. and	EPO; JPO;	
		(heater or (heating adj element))	DERWENT;	
		(IBM TDB	,
_	96	((glass and etching and apparatus).ti. or	USPAT;	2004/05/05 15:19
		(glass and etching and apparatus).ab. or	US-PGPUB;	
		(glass and etching and apparatus).clm.)	EPO; JPO;	
		and (heater or (heating adj element))	DERWENT;	
			IBM_TDB	
-	740	(etch\$3 or bath) with (heater\$1 or	USPĀT;	2004/05/08 15:25
		heating) with (computer or controller)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
1	2.0	(-t-\02 1 () 1)	IBM_TDB	0004/05/00 55 55
_	32	(etch\$3 and (bath or solution or liquid or	USPAT;	2004/05/08 15:28
		etchant)) with (heater\$1 or heating) with	US-PGPUB;	
		(computer or controller)	EPO; JPO;	
			DERWENT; IBM TDB	
	L		TEM TAR	

_	4	(etch\$3 and (bath or solution or liquid or etchant)) with (heater\$1 or heating) with	USPAT; US-PGPUB;	2004/05/08 15:29
		(computer)	EPO; JPO;	
		(compass2)	DERWENT;	
			IBM_TDB	0004/05/00 45 00
_	28	(etch\$3 and (bath or solution or liquid or etchant)) with (heater\$1 or heating) with	USPAT; US-PGPUB;	2004/05/08 15:30
		(controller)	EPO; JPO;	
			DERWENT;	
	2	(etch\$3 and (tank or bath or solution or	IBM_TDB USPAT;	2004/05/08 15:37
-	2	liquid or etchant)) same ((plural or	US-PGPUB;	2004/03/06 13:37
		multiple) with heat\$3 with (zones or	EPO; JPO;	
		regions))	DERWENT;	
_	135	(etch\$3 and (tank or bath or lens or	IBM_TDB USPAT;	2004/05/08 15:42
		solution or liquid or wet)) and ((plural	US-PGPUB;	2001, 00, 00 10112
		or multiple) with heat\$3 with (zones or	EPO; JPO;	
		regions))	DERWENT; IBM TDB	
_	9	(etch\$3 with bath) same (heat\$3 with	USPAT;	2004/05/08 15:43
		(zones or regions))	US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM TDB	
-	34	(etch\$3 with bath) same (computer)	USPAT;	2004/05/08 15:48
			US-PGPUB; EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	4	(etch\$3 with (bath or solution)) same (thermal adj gradient)	USPAT;	2004/05/08 15:51
		(thermal adj gradient)	US-PGPUB; EPO; JPO;	
			DERWENT;	
	1	 (wet adj etch\$3) same (thermal adj	IBM_TDB USPAT;	2004/05/10 12:13
_		gradient)	US-PGPUB;	2004/05/10 12:13
			EPO; JPO;	
			DERWENT; IBM TDB	
_	103	(etch\$3) same (thermal adj gradient)	USPAT;	2004/05/08 15:52
			US-PGPUB;	, , , , , ,
			EPO; JPO; DERWENT;	
			IBM TDB	
-	12	(etch\$3) same (thermal adj gradient) same	USPĀT;	2004/05/08 15:52
		(solution or acid or bath)	US-PGPUB; EPO; JPO;	
			DERWENT;	
	_	(-1.10)	IBM_TDB	
_	5	(etch\$3 and bath) with (heater\$1 or heating) with (computer or controller)	USPAT; US-PGPUB;	2004/05/08 16:02
			EPO; JPO;	
			DERWENT;	
_	1957	((216/24).CCLS.) or ((216/26).CCLS.) or	IBM_TDB USPAT;	2004/05/10 11:30
		((216/31).CCLS.) or ((216/55).CCLS.) or	US-PGPUB;	2004/05/10 11.30
		((216/85).CCLS.) or ((216/87).CCLS.) or	EPO; JPO;	
		((216/94).CCLS.) or ((216/97).CCLS.)	DERWENT; IBM TDB	
-	393	(((216/24).CCLS.) or ((216/26).CCLS.) or	USPAT;	2004/05/10 11:32
		((216/31).CCLS.) or ((216/55).CCLS.) or	US-PGPUB;	
		((216/85).CCLS.) or ((216/87).CCLS.) or ((216/94).CCLS.) or ((216/97).CCLS.)) and	EPO; JPO; DERWENT;	
		(heater or heating) and (solution or bath)	IBM TDB	
-	48	((etch-rate or (etch adj rate)) with	USPAT;	2004/05/10 11:34
		<pre>increas\$3 with temperature) same (solution or bath)</pre>	US-PGPUB; EPO; JPO;	
		' '	DERWENT;	
			IBM_TDB	

Page 7

	26	(156/345.15).ccls. and (heating or heater)	USPAT; US-PGPUB;	2004/05/10 11:45
			EPO; JPO; DERWENT;	
	28	(156/345.22).ccls. and (heating or heater)	IBM_TDB USPAT;	2004/05/10 11:46
	20	(1507545.227.0015. and (heating of heater)	US-PGPUB;	2004/03/10 11:40
			EPO; JPO; DERWENT;	
			IBM TDB	
-	13	(156/345.27).ccls. not plasma	USPĀT;	2004/05/10 11:50
			US-PGPUB; EPO; JPO;	
			DERWENT;	
_	1911	(134/1).CCLS.	IBM_TDB USPAT;	2004/05/10 11:54
		(101,71,10020)	US-PGPUB;	2001,00,10 11101
		·	EPO; JPO; DERWENT;	
			IBM_TDB	
_	64	(radiation and etch\$3 and (smoothness or glass or lens\$2 or planar\$4) and (bath or	USPAT; US-PGPUB;	2004/05/10 11:58
		solution)).ab.	EPO; JPO;	
		,	DERWENT;	
_	21	 (apparatus and polish\$3 and heater\$1 and	IBM_TDB USPAT;	2004/05/10 12:15
		(computer or controller)).clm.	US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM_TDB	
-	3	(polish\$3 or etch\$3) same (thermal adj gradient) same (boundary adj layer)	USPAT; US-PGPUB;	2004/05/10 12:14
		gradient, came (acanalizy day rayer,	EPO; JPO;	
			DERWENT; IBM TDB	
-	168	((polish\$3 or etch\$3) and (solution or	USPĀT;	2004/05/10 12:24
		bath or etchant) and ((heating adj element\$1) or heater\$1)).clm.	US-PGPUB; EPO; JPO;	
		element() of neater()).cim.	DERWENT;	
_	22	((polish\$3 or etch\$3) and (solution or	IBM_TDB USPAT;	2004/05/10 12:18
_	22	bath or etchant) and interferomet\$7).clm.	US-PGPUB;	2004/05/10 12:18
			EPO; JPO;	
			DERWENT; IBM TDB	
_	1049	1 14	USPĀT;	2004/05/10 12:35
		element\$1) or heater\$1) near2 (array or plurality)) and (bath or solution or	US-PGPUB; EPO; JPO;	
		etchant or acid) and (computer or	DERWENT;	
_	139	control\$3 or monitor\$3 or microprocessor) (polish\$3 or etch\$3).ab. and (((heating	IBM_TDB USPAT;	2004/05/10 12:31
		adj element\$1) or heater\$1) near2 (array	US-PGPUB;	
		or plurality)) and (bath or solution or etchant or acid) and (computer or	EPO; JPO; DERWENT;	
		control\$3 or monitor\$3 or microprocessor)	IBM_TDB	000445=44=
_	688	((polish\$3 or etch\$3) and (((heating adj element\$1) or heater\$1) near2 (array or	USPAT; US-PGPUB;	2004/05/10 12:32
		plurality)) and (bath or solution or	EPO; JPO;	
		<pre>etchant or acid) and (computer or control\$3 or monitor\$3 or microprocessor))</pre>	DERWENT; IBM TDB	
		not (inkjet or ink-jet or (ink adj jet) or	1011_100	
		<pre>printhead or print-head or (print adj head))</pre>		
-	441	((polish\$3 or etch\$3) and (((heating adj	USPAT;	2004/05/10 12:33
		element\$1) or heater\$1) near2 (array or plurality)) and (bath or solution or	US-PGPUB;	
		etchant or acid) and (computer or	EPO; JPO; DERWENT;	
		control\$3 or monitor\$3 or microprocessor))	IBM_TDB	
		not (inkjet or ink-jet or (ink adj jet) or printhead or print-head or (print adj		
		head) or plasma)		

-	7	(polish\$3 or etch\$3) and (bath or solution	USPAT;	2004/05/10 12:38
	-	or etchant or acid) and (((heating adj	US-PGPUB;	
	l	element\$1) or heater\$1) with (array or	EPO; JPO;	
	1	plurality) with (independently adj	DERWENT;	
	67	controlled))	IBM_TDB USPAT;	2004/05/10 12:39
_	67	1 1 1 1 2 2 2	USPAT; US-PGPUB;	2004/05/10 12:39
	1	with (array or plurality) with	EPO; JPO;	1
	1	(independently adj controlled))	DERWENT;	
			IBM TDB	
	8	(("4343116") or ("5605600") or ("5795493")	USPAT;	2004/05/10 15:00
_	0	or ("4804977")).PN.	US-PGPUB;	2004/03/10 13:00
		OI (40045/7)).IN.	EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	15	(rushford or britten).in. and (polish\$3 or	USPAT;	2004/05/10 15:14
		etch\$3)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	536		USPAT;	2004/05/10 15:25
	1	etch\$3) and glass).ab. and (solution or	US-PGPUB;	
1]	etchant or acid or solvent)	EPO; JPO;	
İ	i		DERWENT;	
1		[IBM_TDB	0004/05/10 55 5
_	29		USPAT;	2004/05/10 15:20
İ		etch\$3) and glass).ab. and (solution or	US-PGPUB;	
		etchant or acid or solvent) and computer	EPO; JPO;	
			DERWENT;	
	17	(/lagar or radiation) and (malight) or	IBM_TDB USPAT;	2004/05/10 15:58
_	''	((laser or radiation) and (polish\$3 or etch\$3) and glass).ab. and (solution or	US-PGPUB;	2004/05/10 15:58
		etchant or acid or solvent) and ((heating	EPO; JPO;	1
		adj element\$1) or heater\$1)	DERWENT;	
		duj ciementori, or neuterori,	IBM TDB	
_	19	((laser-assisted) and etch\$3).ab.	USPAT;	2004/05/10 16:12
		((label abbibeed) and econfo, lab.	US-PGPUB;	2001,00,10 10:12
			EPO; JPO;	
			DERWENT;	
	j		IBM TDB	
	4	, , , ,	USPAT	2004/05/10 16:08
		"6257255" "2001/0045223 "		
		"2002/0074023").PN.		
-	357	(laser and (wet adj etch\$3)).ab.	USPAT;	2004/05/10 16:14
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
1_	136	(laser with (wet adj etch\$3)).ab.	IBM_TDB USPAT;	2004/05/10 16:14
	130	(tabel with (wet ad) etchys//.ab.	US-PGPUB;	2004/03/10 10:14
	-		EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	115	(216/97).ccls. and (laser or radiation or	USPĀT;	2004/05/11 13:37
		beam)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
 -	5	(216/97).ccls. and (interferometer)	USPĀT;	2004/05/11 13:32
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	0046	/-1ith1i-hA2\	IBM_TDB	0004/05/44 45 55
_	2246	(glass with polish\$3) and (laser or	USPAT;	2004/05/11 13:38
		radiation or beam) and etch\$3	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
L	L		IBM_TDB	

-	137		USPAT;	2004/05/11 13:39
		radiation or beam) and etch\$3) and	US-PGPUB;	
		interferometer	EPO; JPO;	
			DERWENT;	
			IBM_TDB	0004/05/11 10 00
_	57	1 , , , ,	USPAT;	2004/05/11 13:39
		radiation or beam) and etch\$3) and	US-PGPUB;	
		interferometer and computer	EPO; JPO;	
			DERWENT;	
			IBM_TDB	0004/05/11 15 00
-	457	(laser adj (assisted or induced or	USPAT;	2004/05/11 15:32
		controlled)) with etch\$3	US-PGPUB;	ļ
			EPO; JPO;	
			DERWENT;	
	110		IBM_TDB	2004/05/11 15 00
_	113	((laser adj (assisted or induced or	USPAT;	2004/05/11 15:22
		controlled)) with etch\$3) and cool\$3	US-PGPUB;	i
			EPO; JPO;	
			DERWENT;	
		//7	IBM_TDB	2004/05/11 15:26
_	58	((laser adj (assisted or induced or	USPAT;	2004/05/11 15:36
		controlled)) with etch\$3).ti.	US-PGPUB;	
		·	EPO; JPO; DERWENT;	
1_	28	(cooling adj2 etchant)	IBM_TDB USPAT;	2004/05/11 15:37
_	28	(Cooling adjz etchant)		2004/05/11 15:37
			US-PGPUB; EPO; JPO;	
			DERWENT;	1
			IBM TDB	
	14	(cooling adj etchant)	USPAT;	2004/05/11 15:39
-	14	(cooring adj etchant)	US-PGPUB;	2004/05/11 15:39
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
	42	(temperature adj control) with etch\$3 with	USPAT;	2004/05/11 15:42
	42	(bath or solution or tank)	US-PGPUB;	2004/03/11 13:42
		(Bath of Solution of tank)	EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	21	(etchant or (etching adj solution)) adj2	USPAT;	2004/05/11 15:44
		cooled	US-PGPUB;	2001/03/11 13:11
	İ	000104	EPO; JPO;	
			DERWENT:	
			IBM TDB	
	48	(temperature adj control) with etchant	USPAT;	2004/05/11 15:45
			US-PGPUB;	1000, 00, 11 10, 10
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	768	(134/105).CCLS.	USPAT;	2004/05/12 11:12
1			US-PGPUB;	,
	ļ		EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	110	((134/105).CCLS.) and (computer or	USPAT;	2004/05/12 11:12
		controller)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	50	((134/105).CCLS.) and $(computer or$	USPĀT;	2004/05/12 11:12
		controller) and (glass or polish\$3 or	US-PGPUB;	
		lens\$2 or etch\$3)	EPO; JPO;	
			DERWENT;	
		1010 (101 011	IBM_TDB	
-	898	(219/121.84).CCLS.	USPAT;	2004/05/12 16:07
			US-PGPUB;	
			EPO; JPO;	
1			DERWENT;	
			IBM_TDB	

-	334	(219/121.76).CCLS.	USPAT;	2004/05/12 11:44
	001	(813) 1811 (0) 100201	US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM_TDB	
-	1031	(219/121.68).CCLS.	USPAT; US-PGPUB;	2004/05/12 11:47
			EPO; JPO;	
			DERWENT;	
_	1228	(219/121.69).CCLS.	IBM_TDB USPAT;	2004/05/12 11:46
	1220	(213) 121.03) . Codo.	US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM TDB	
-	775	(219/121.68).CCLS.	USPAT;	2004/05/12 11:48
_	102	(((219/121.68).CCLS.) or	US-PGPUB USPAT;	2004/05/12 11:49
	102	((219/121.69).CCLS.)) and (etchant or	US-PGPUB;	
ĺ		(etch\$ adj (solution or bath)))	EPO; JPO; DERWENT;	
			IBM TDB	
-	6	(laser and machining).ti. and (etchant or	USPAT;	2004/05/12 13:32
		solution).clm.	US-PGPUB; EPO; JPO;	
			DERWENT;	
	111	(laser and machining).ti. and (plurality	IBM_TDB USPAT;	2004/05/12 13:32
_	111	or array).clm.	US-PGPUB;	2004/03/12 13.32
			EPO; JPO;	
			DERWENT; IBM TDB	
_	1348	((laser with (plurality or array)) and	USPĀT;	2004/05/12 13:36
		(etch\$3 or machin\$3 or polish\$3)).clm.	US-PGPUB; EPO; JPO;	
		·	DERWENT;	
	017		IBM_TDB	2004/05/10 12 26
_	817	(((laser with (plurality or array)) and (etch\$3 or machin\$3 or polish\$3)).clm.)	USPAT; US-PGPUB;	2004/05/12 13:36
		and (glass or lens\$2)	EPO; JPO;	
			DERWENT; IBM TDB	
_	225	((laser with (plurality or array)) and	USPĀT;	2004/05/12 13:37
		<pre>(etch\$3 or machin\$3 or polish\$3) and (computer or controller)).clm.</pre>	US-PGPUB; EPO; JPO;	
		(computer of controllery).clm.	DERWENT;	
į	100	(//	IBM_TDB	2004/05/10 12:27
-	102	((laser near2 (plurality or array)) and (etch\$3 or machin\$3 or polish\$3) and	USPAT; US-PGPUB;	2004/05/12 13:37
		(computer or controller)).clm.	EPO; JPO;	
			DERWENT; IBM TDB	
-	60	(photo-processing or photo-machining).ti.	USPAT;	2004/05/12 15:48
		not film	US-PGPUB; EPO; JPO;	
			DERWENT;	
	0010	(-t-ttt	IBM_TDB	2004/05/20 25 52
_	2313	(etchant or (etch\$3 adj solution)) same laser	USPAT; US-PGPUB;	2004/05/12 15:50
			EPO; JPO;	
			DERWENT; IBM TDB	
_	41	((etchant or (etch\$3 adj solution)) same	USPAT;	2004/05/12 15:57
		laser).ti.	US-PGPUB;	
			EPO; JPO; DERWENT;	
	F.4	(/	IBM_TDB	0004/05/10 15 55
_	51	((etchant or (etch\$3 adj solution)) same laser).ab. and glass	USPAT; US-PGPUB;	2004/05/12 15:57
		, , , , , , , , , , , , , , , , , , , ,	EPO; JPO;	
			DERWENT;	
L	L		IBM_TDB	

				105 100 15 00
_	112	(219/121.2).CCLS.	USPAT;	2004/05/12 16:08
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	1
	87	(219/121.19).CCLS.	USPAT;	2004/05/12 16:08
_	67	(213/121.13/.0000.	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
	,		USPAT;	2004/05/12 16:08
_	157	(219/121.33).CCLS.	1	2004/03/12 10:00
			US-PGPUB;	
			EPO; JPO;]
			DERWENT;	ļ
	ļ		IBM_TDB	
	310	(219/121.35).CCLS.	USPAT;	2004/05/12 16:15
		,	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	1
			IBM TDB	1
	00	(250/649) CCI C	USPAT;	2004/05/12 16:16
-	98	(359/648).CCLS.	US-PGPUB;	
Ì			EPO; JPO;	
			1	
			DERWENT;	1
			IBM_TDB	0004/05/10 16:07
-	65	(216/97).CCLS. and laser	USPAT;	2004/05/12 16:27
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
	18	("3954534" "4183780" "4260649"	USPAT	2004/05/12 16:32
_	10	"4391683" "4478677" "4705593"		
	1	1331333		
		"5041849" "5122818" "5229793"		
		"5316640" "5456798" "5565113"		
		"5591490" "5705079" "5919607").PN.] _	0004/05/10 16:34
_	2	("4876690" "4904340").PN.	USPAT	2004/05/12 16:34
_	1	1991-075416.NRAN.	DERWENT	2004/05/12 16:35
_	3	("4379022" "4439294" "4751779").PN.	USPAT	2004/05/12 16:35
_	3	("4379022" "4439294" "4751779").PN.	USPAT	2004/05/12 16:36
	18	("3954534" "4183780" "4260649"	USPAT	2004/05/12 16:37
1 -		"4391683" "4478677" "4705593"		
		"4782350" "4842782" "5028937"		
1				
1		"5316640" "5456798" "5565113"		
1		"5591490" "5705079" "5919607").PN.	LICDAM.	2004/05/13 12:23
-	2	("5374291").PN.	USPAT;	2004/03/13 12.23
			US-PGPUB;	
	1		EPO; JPO;	
1	1		DERWENT;	1
			IBM_TDB	
_	2	("6362453").PN.	USPAT;	2004/05/13 11:57
			US-PGPUB;	
			EPO; JPO;	1
			DERWENT;	
			IBM TDB	
		(#4200476# #4470677# #4500020#	USPAT	2004/05/13 12:20
-	11		OSEMI	2004/03/13 12.20
	1	"4970366" "5061840" "5326426"		
		"5354633" "5460284" "5567484"		
		"5656186" "6049058").PN.		
1 -	1	2000-273882.NRAN.	DERWENT	2004/05/13 12:23
		<u> </u>		